2SC3975

Silicon NPN triple diffusion planar type

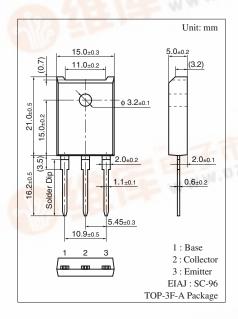
For high breakdown voltage high-speed switching

■ Features

- High-speed switching
- High collector to base voltage V_{CBO}
- Wide area of safe operation (ASO)
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25$ °C

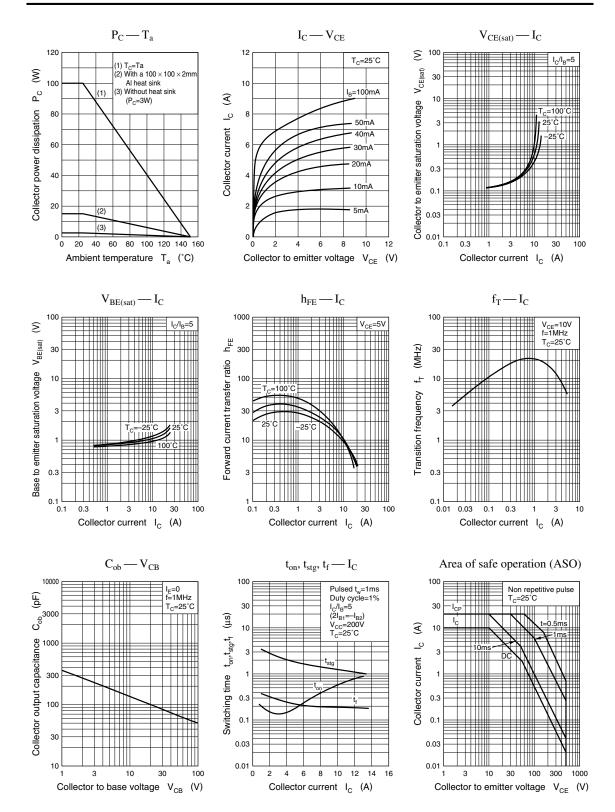
Parameter		Symbol	Rating	Unit
Collector to base voltage		V _{CBO}	800	V
Collector to emitter voltage		V _{CES}	800	V
5/6 =		V _{CEO}	500	V
Emitter to base voltage		V_{EBO}	8	V
Peak collector current		I_{CP}	20	A
Collector current		I_C	10	A
Base current		I_{B}	5	A
Collector power	$T_C = 25^{\circ}C$	P _C	100	W
dissipation	$T_a = 25^{\circ}C$		3	
Junction temperature		T _j	150	°C
Storage temperature		$T_{\rm stg}$	-55 to +150	°C



■ Electrical Characteristics T_C = 25°C

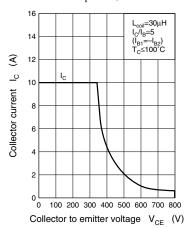
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 800 \text{ V}, I_{E} = 0$			100	μΑ
Emitter cutoff current	I_{EBO}	$V_{EB} = 5 \text{ V}, I_{C} = 0$			100	μΑ
Collector to emitter voltage	V_{CEO}	$I_C = 10 \text{ mA}, I_B = 0$	500			V
Forward current transfer ratio	h _{FE1}	$V_{CE} = 5 \text{ V}, I_{C} = 0.1 \text{ A}$	15			
	h _{EF2}	$V_{CE} = 5 \text{ V}, I_{C} = 6 \text{ A}$	8			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 6 \text{ A}, I_B = 1.2 \text{ A}$			1.0	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = 6 \text{ A}, I_B = 1.2 \text{ A}$			1.5	V
Transition frequency	f_T	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time	t _{on}	$I_C = 6 \text{ A}, I_{B1} = 1.2 \text{ A}, I_{B2} = -2.4 \text{ A},$			1.0	μs
Storage time	t _{stg}	$V_{CC} = 200 \text{ V}$			3.0	μs
Fall time	t _c				0.3	IIS

2SC3975 Power Transistors

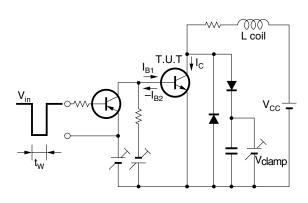


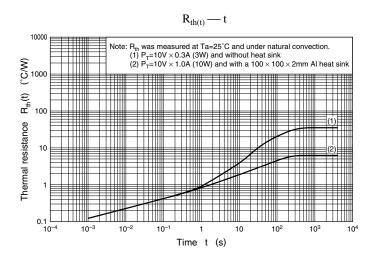
Power Transistors 2SC3975

Area of safe operation, reverse bias ASO



Reverse bias ASO measuring circuit





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